

# HIGH-SPEED LOW PROFILE OPEN-PIN-FIELD

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?LPAM](http://www.samtec.com?LPAM)

**Insulator Material:**

Black LCP

**Terminal Material:**

Copper Alloy

**Plating:**

Au or Sn over

50 μ" (1.27 μm) Ni

**Current Rating:**

2.2 A per pin

(6 adjacent pins powered)

**Working Voltage:**

250 VAC

**RoHS Compliant:**

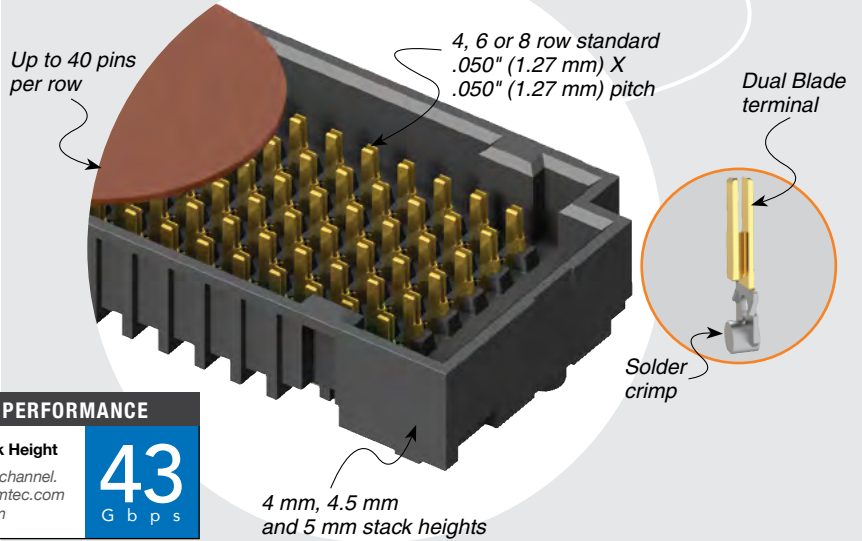
Yes

**Lead-Free Solderable:**

Yes

**Mates with:**

LPAF



### HIGH-SPEED CHANNEL PERFORMANCE

LPAM/LPAF @ 5 mm Mated Stack Height

Rating based on Samtec reference channel.  
For full SI performance data visit [Samtec.com](http://Samtec.com)  
or contact [SIG@samtec.com](mailto:SIG@samtec.com)

**43**  
Gbps

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



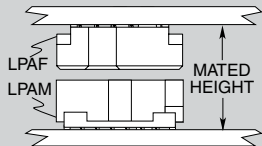
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## ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
  - Other pins/row and row counts
  - Other Gold plating options
- Contact Samtec.

<b>LPAM</b>	<b>NO. PINS PER ROW</b>	<b>LEAD STYLE</b>	<b>PLATING OPTION</b>	<b>NO. OF ROWS</b>	<b>SOLDER TYPE</b>	<b>K</b>	<b>TR</b>
	-10, -20, -30, -40 (Per Row)	-01.0 = (1.0 mm) .039" -01.5 = (1.5 mm) .060"	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -06 = Six Rows -08 = Eight Rows	-2 = Lead-Free Solder Crimp	-K = Polyimide film Pick & Place Pad	-TR = Tape & Reel

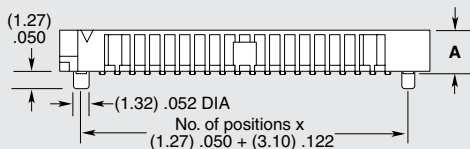
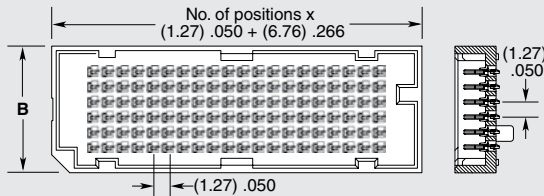
## MATED HEIGHT



NO. OF ROWS	B
-04	(8.18) .322
-06	(10.72) .422
-08	(13.26) .522

MATED HEIGHT*		
LPAM LEAD STYLE	LPAF LEAD STYLE	
	-03.0	-03.5
-01.0	(4.00) .157	(4.50) .177
-01.5	(4.50) .177	(5.00) .197

\*Processing conditions will affect mated height.



LEAD STYLE	A
-01.0	(3.68) .145
-01.5	(4.19) .165

Note: Patent Pending

Note: Some sizes, styles and options are non-standard, non-returnable.